

WHAT IS CLAIMED IS:

1. An electrode and wiring forming method,
comprising:

5 a base pattern forming step of forming a base
pattern on a substrate;

an absorbing step of absorbing an organic
metallic compound into the base pattern; and

a baking step of baking the base pattern in
which the organic metallic compound is absorbed,
10 wherein the base pattern forming step includes:

a step of applying a photosensitive resin
containing a water-soluble photosensitive resin
component and a water-soluble metallic compound onto
the substrate; and

15 a step of exposing the photosensitive resin.

2. An electrode and wiring forming method
according to claim 1, wherein a compounding ratio of
the water-soluble metallic compound to the
20 photosensitive resin component is 1.0 % by weight to
20 % by weight.

3. An electrode and wiring forming method
according to claim 2, wherein the water-soluble
25 metallic compound is a water-soluble metallic
compound including rhodium, bismuth, ruthenium,
vanadium, chromium, tin, lead, or silicon.

4. An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a complex and a ligand thereof is a nitrogen-containing compound.

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5. An electrode and wiring forming method according to claim 4, wherein the nitrogen-containing compound is a nitrogen-containing compound having at most 8 carbon atoms.

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6. An electrode and wiring forming method according to claim 2, wherein the organic metallic compound is a platinum complex.

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7. A base pattern forming material for electrode and wiring material absorption comprising a water-based solution containing a water-soluble photosensitive resin component and a water-soluble metallic compound.

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8. A base pattern forming material for electrode and wiring material absorption according to claim 7, wherein a compounding ratio of the water-soluble metallic compound to the photosensitive resin component is 1.0 % by weight or more and 20 % by weight or less.

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9. A base pattern forming material for
electrode and wiring material absorption according to
claim 8, wherein the water-soluble metallic compound
is a water-soluble metallic compound including
5 rhodium, bismuth, ruthenium, vanadium, chromium, tin,
lead, or silicon.

10. A base pattern forming material for
electrode and wiring material absorption according to
10 claim 8, wherein the water-soluble photosensitive
resin component is one of a polyvinyl alcohol-based
resin and a polyvinyl pyrrolidone-based resin.

11. A method of manufacturing an image-forming
15 apparatus including a plurality of electron-emitting
devices and an image-forming member for forming an
image by irradiation of electron beams emitted from
the electron-emitting devices, comprising forming at
least one of an electrode and a wiring by the method
20 according to claim 1.